

2-4GHz Driver

GaAs Monolithic Microwave IC

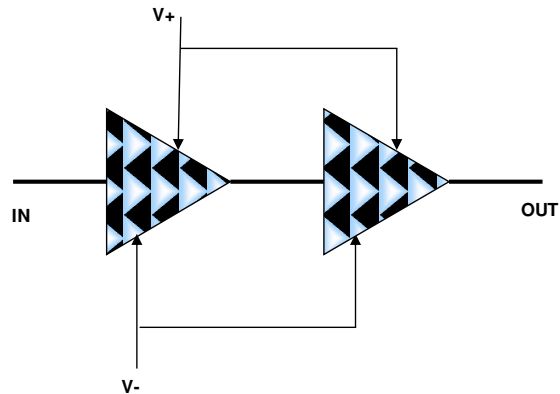
Description

The CHA4105-99F is a monolithic two-stage driver amplifier delivering 24dBm output power @ 1dB gain compression in the 2-4GHz frequency range.

It is designed for a wide range of applications, from military to commercial communication systems.

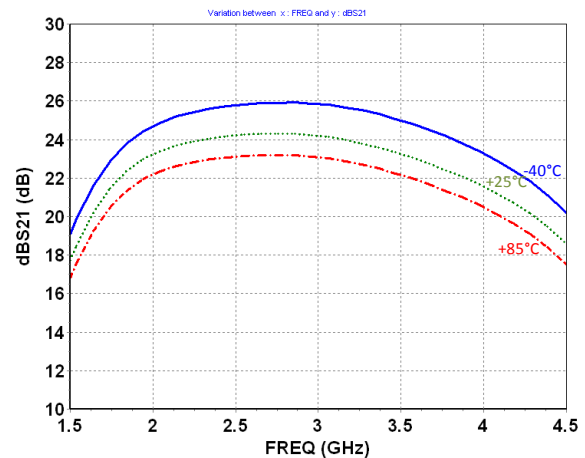
The circuit is manufactured with a pHEMT process, 0.25µm gate length, via holes through the substrate, air bridges and electron beam gate lithography.

It is available in chip form.



Main Features

- Broadband performances: 2-4GHz
- 24dBm @ 1dB gain compression
- 23dB Gain
- DC bias: V+ = 5V ; V- = -5V
- DC power consumption: 180mA
- Chip size: 2.07 x 1.6 x 0.1 mm



Main Characteristics

Tamb. = +25 °C

| Symbol | Parameter | Min | Typ | Max | Unit |
|--------|-------------------------|-----|-----|-----|------|
| Freq | Frequency range | 2 | | 4 | GHz |
| Gain | Linear Gain | | 23 | | dB |
| P_1dB | Output Power @1dB comp. | | 24 | | dBm |

ESD Protections: Electrostatic discharge sensitive device. Observe handling precautions!

Main Characteristics

Tamb.= +25°C

| Symbol | Parameter | Min | Typ | Max | Unit |
|---------|--|-----|-----|-----|------|
| Freq | Frequency range | 2 | | 4 | GHz |
| Gain | Linear Gain | | 23 | | dB |
| RL_in | Input Return Loss | | 15 | | dB |
| RL_out | Output Return Loss | | 18 | | dB |
| P_1dB | Output power @ 1dB gain compression | | 24 | | dBm |
| PAE_1dB | Power Added Efficiency @ 1dBcomp. | | 28 | | % |
| V+ | Positive supply voltage | | 5 | | V |
| V- | Negative supply voltage | | -5 | | V |
| I+ | Positive supply quiescent current ⁽¹⁾ | | 180 | | mA |
| I- | Negative supply quiescent current | | 5 | | mA |
| I+_1dB | Positive current @ 1dB gain compression | | 220 | | mA |

These values are representative of onboard measurements as defined on the drawing in paragraph "Evaluation mother board".

⁽¹⁾ Parameter can be adjusted by tuning of V-.

Absolute Maximum Ratings ⁽¹⁾

Tamb.= +25°C

| Symbol | Parameter | Values | Unit |
|--------|-------------------------------------|-------------|------|
| V+ | Positive supply voltage | 6.5V | V |
| I+ | Positive supply quiescent current | 240 | mA |
| V- | Negative supply voltage | -3.75 | V |
| Tj | Junction temperature ⁽²⁾ | 175 | °C |
| Cmp | Compression level | 6 | dB |
| I+_sat | Supply current in saturation | 320 | mA |
| Ta | Operating temperature range | -40 to +85 | °C |
| Tstg | Storage temperature range | -55 to +155 | °C |

⁽¹⁾ Operation of this device above anyone of these parameters may cause permanent damage.

⁽²⁾ Thermal Resistance channel to ground paddle = 101 °C/W for T= +85°C.

Typical on-wafer Sij parameters

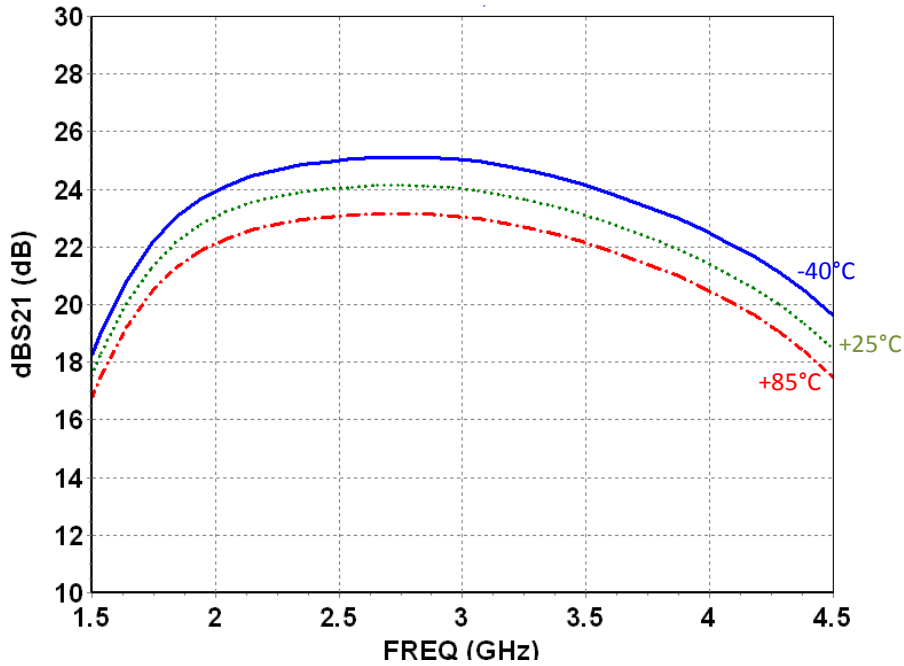
Tamb.= +25°C, V+ = +8V, I+ = 180mA

| Freq (GHz) | S11 (dB) | PhS11 (°) | S12 (dB) | PhS12 (°) | S21 (dB) | PhS21 (°) | S22 (dB) | PhS22 (°) |
|------------|----------|-----------|----------|-----------|----------|-----------|----------|-----------|
| 0.10 | -0.36 | -6.99 | -69.84 | 178.30 | -33.96 | -95.60 | -0.58 | -15.89 |
| 0.50 | -1.29 | -27.40 | -39.33 | -1.72 | -11.29 | 117.70 | -1.96 | -72.56 |
| 1.00 | -1.94 | -61.11 | -39.27 | -124.00 | -1.79 | 146.90 | -6.02 | -141.70 |
| 1.50 | -8.45 | -129.10 | -40.31 | 125.30 | 17.67 | 68.32 | -14.87 | 154.80 |
| 2.00 | -19.45 | -9.13 | -42.17 | 33.05 | 22.70 | -40.78 | -39.04 | -50.42 |
| 2.50 | -16.35 | -40.67 | -42.04 | -40.67 | 23.65 | -119.90 | -20.64 | -64.11 |
| 3.00 | -27.33 | -65.04 | -41.93 | -107.90 | 23.97 | 167.90 | -19.19 | -97.03 |
| 3.50 | -18.68 | 37.43 | -42.83 | -173.80 | 23.21 | 98.09 | -24.13 | -50.70 |
| 4.00 | -19.87 | -55.35 | -44.60 | 126.30 | 21.53 | 30.41 | -14.51 | -33.10 |
| 4.50 | -9.94 | 160.10 | -46.99 | 66.06 | 18.51 | -37.00 | -9.41 | -46.44 |
| 5.00 | -4.07 | 106.30 | -50.19 | 1.40 | 13.84 | -95.76 | -6.39 | -63.91 |
| 5.50 | -2.17 | 74.95 | -54.83 | -50.90 | 9.24 | -141.90 | -4.74 | -79.58 |
| 6.00 | -1.47 | 54.99 | -57.93 | -75.28 | 5.80 | 176.20 | -3.73 | -92.33 |
| 6.50 | -1.27 | 41.32 | -56.29 | -107.10 | 3.30 | 127.00 | -3.02 | -102.30 |
| 7.00 | -1.01 | 32.22 | -59.51 | -174.20 | -1.03 | 63.07 | -2.30 | -110.50 |
| 7.50 | -0.65 | 23.53 | -73.34 | 139.70 | -8.82 | 11.05 | -1.71 | -119.30 |
| 8.00 | -0.48 | 15.71 | -65.74 | -158.40 | -16.52 | -22.61 | -1.30 | -127.50 |
| 8.50 | -0.41 | 9.02 | -70.70 | 76.88 | -23.22 | -47.81 | -0.98 | -134.70 |
| 9.00 | -0.34 | 3.12 | -75.00 | -91.93 | -28.39 | -70.68 | -0.76 | -141.20 |
| 9.50 | -0.28 | -2.20 | -67.47 | 23.62 | -33.03 | -93.57 | -0.57 | -147.30 |
| 10.00 | -0.23 | -7.02 | -57.14 | -31.86 | -36.77 | -111.10 | -0.45 | -153.30 |

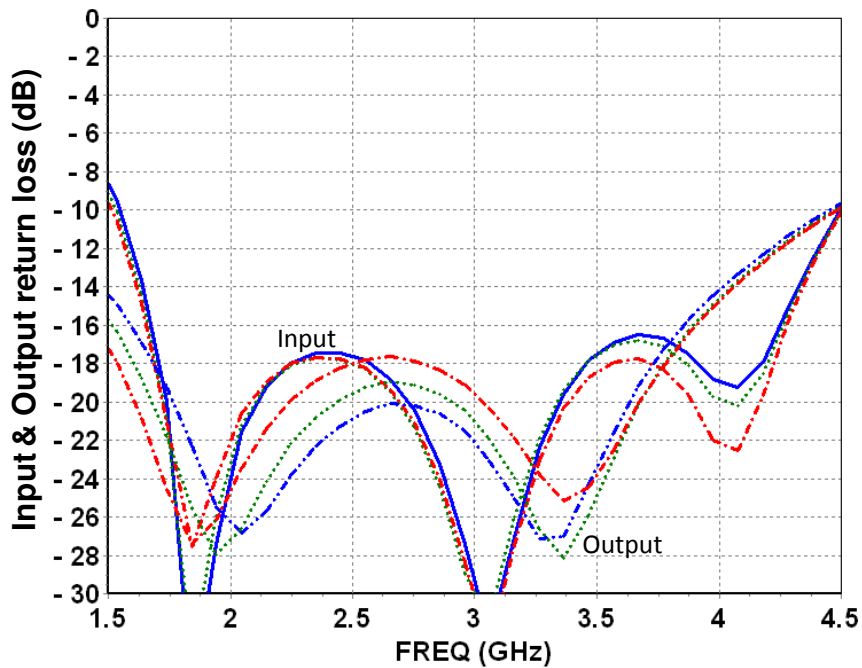
Typical Test fixture Measurements

V+ = +5V, V- = -5V, I+ = 180mA, I- = 2mA

Linear Gain



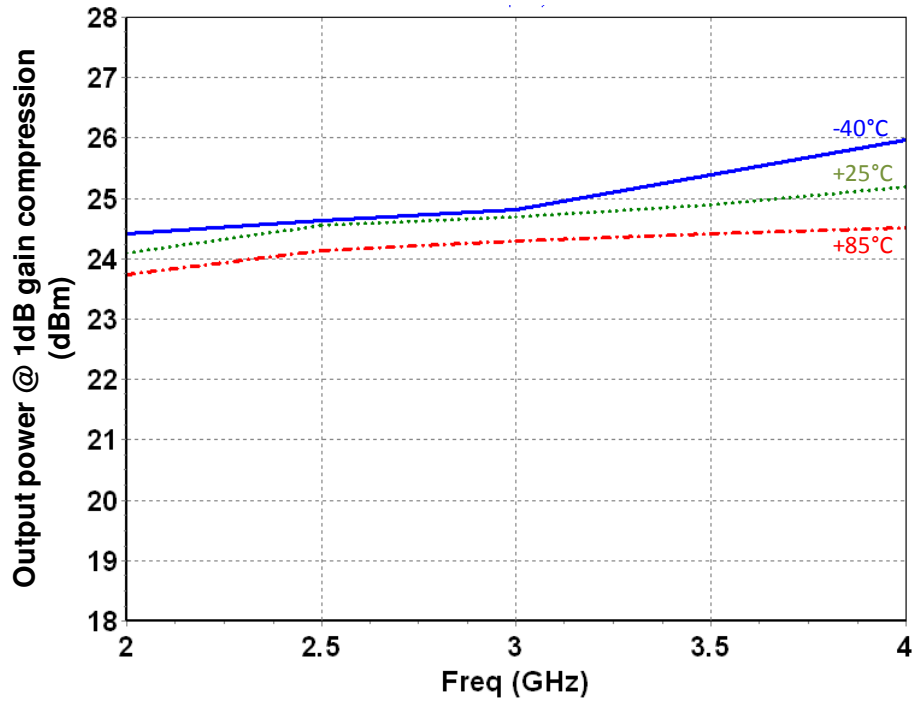
In/out Return Loss



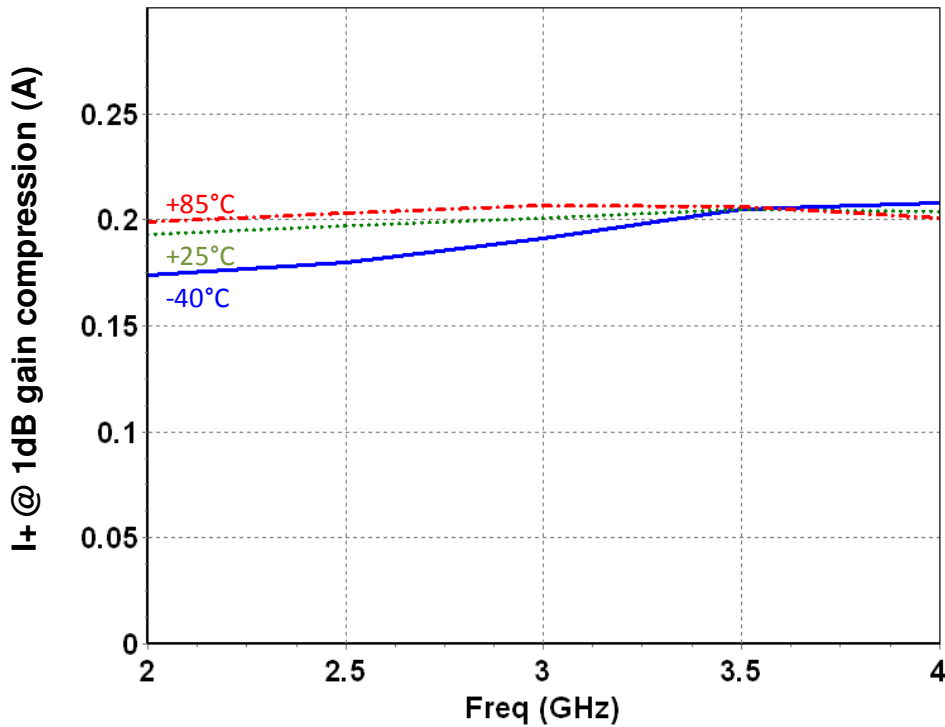
Typical Test fixture Measurements

V+ = +5V, V- = -5V, I+ = 180mA, I- = 2mA

Output power @ 1dB gain compression versus Frequency & Temperature



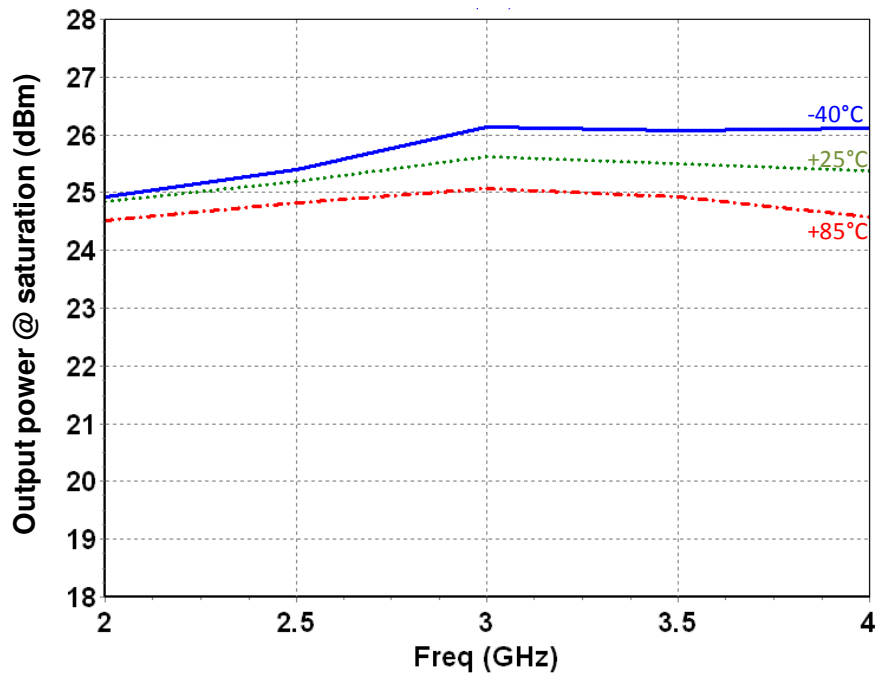
Positive supply current @ 1dB gain compression versus Frequency & Temperature



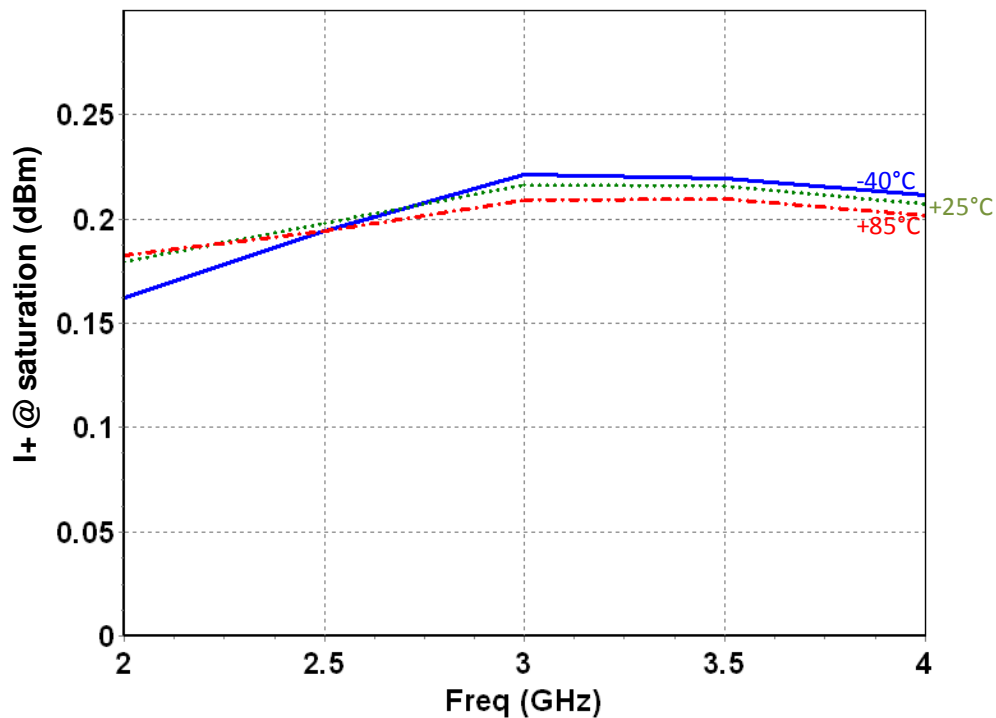
Typical Test fixture Measurements

V+ = +5V, V- = -5V, I+ = 180mA, I- = 2mA

Output power @ saturation versus Frequency & Temperature

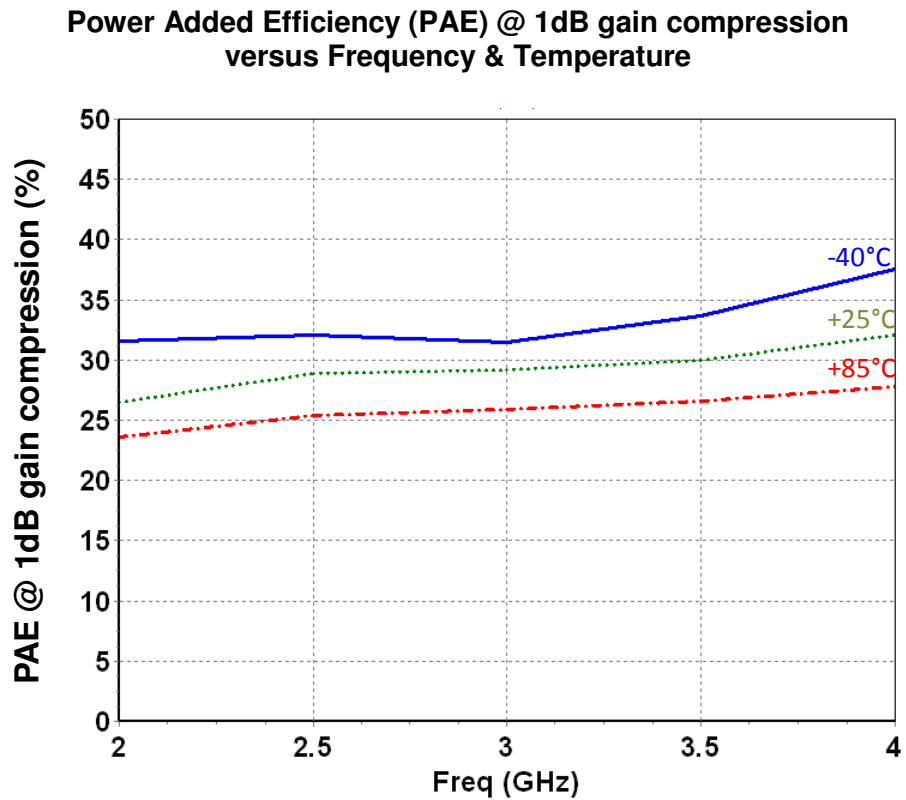


Positive supply current @ saturation versus Frequency & Temperature

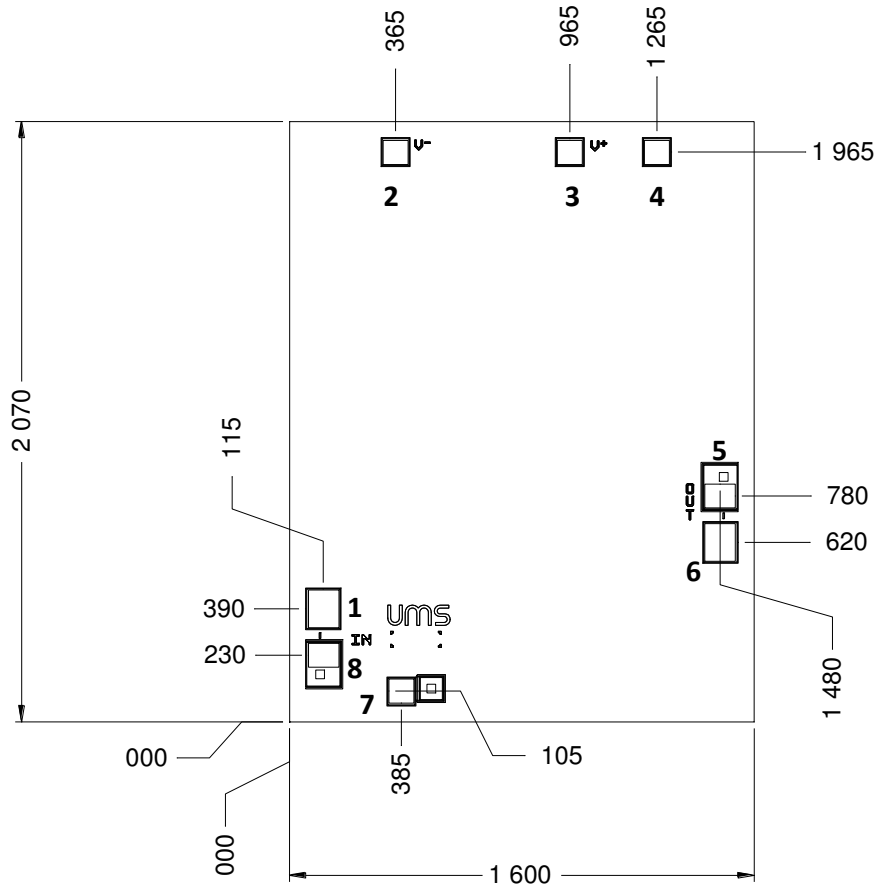


Typical Test fixture Measurements

$V_+ = +5V$, $V_- = -5V$, $I_+ = 180mA$, $I_- = 2mA$



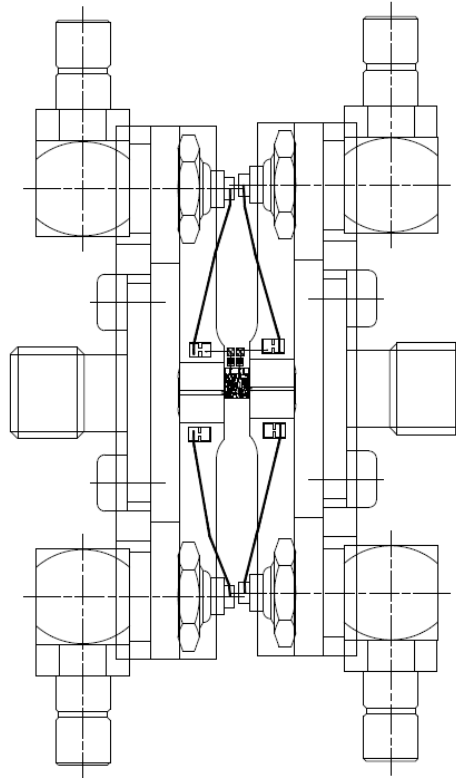
Mechanical data



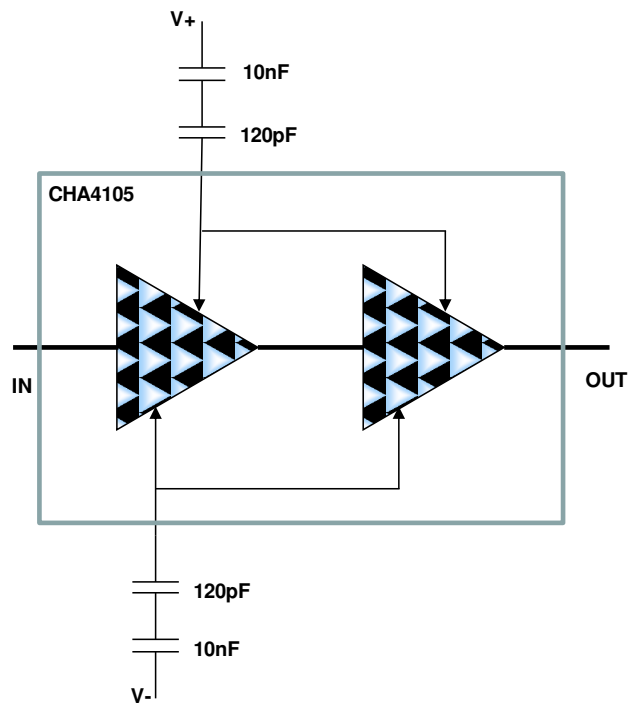
All dimensions are in micrometers
 Chip size = 2070x1600 ±35µm
 Chip thickness = 100µm ±10µm
 RF pads (1, 5) = 122 x 144µm²
 DC pads (2, 3, 4) = 100 x 100µm²

| Pin number | Pin name | Description |
|------------|----------|------------------------------|
| 1 | IN | Input RF |
| 2 | -V | Gate supply voltage |
| 3 | +V | Drain supply voltage |
| 4, 6, 7, 8 | GND | Ground (no bonding required) |
| 5 | OUT | Output RF |

Test fixture 61498835



Recommended assembly plan



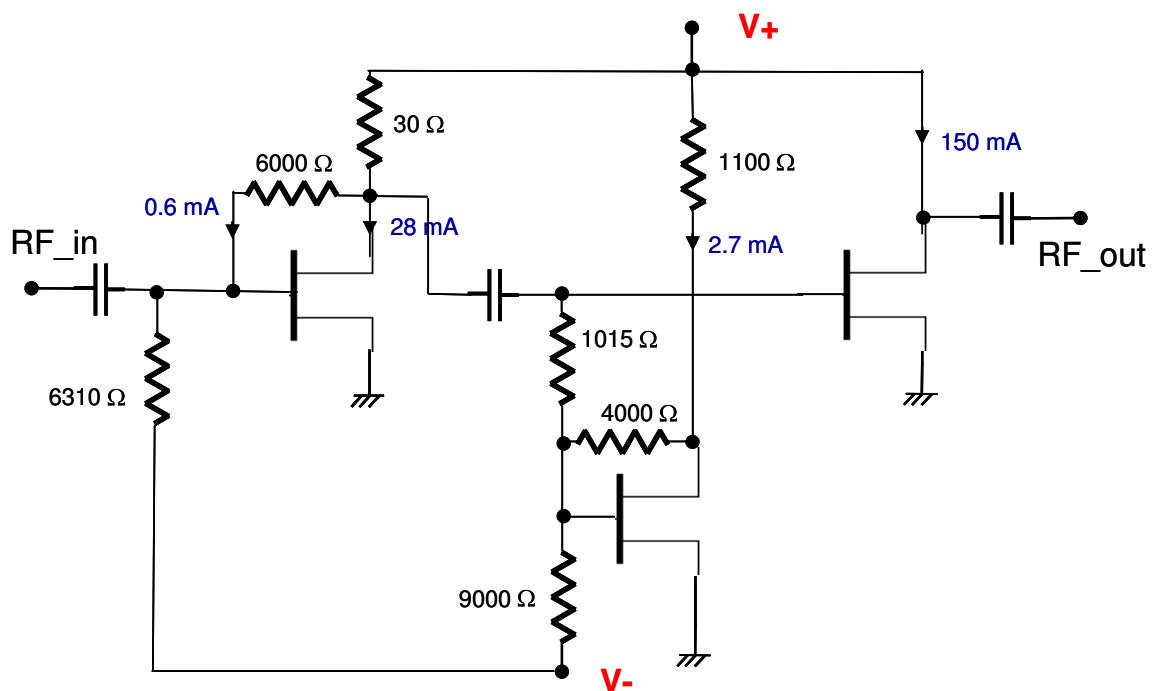
Bonding recommendations

The RF, DC and modulation port inter-connections should be done according to the following table:

| Port | Connection |
|---|---|
| IN (pad 1) | Inductance (L_{bonding}) = 0.3nH 400 μm length with wire diameter of 25 μm x2 |
| OUT (pad 5) | Inductance (L_{bonding}) = 0.3nH 400 μm length with wire diameter of 25 μm x2 |
| DC pads to 1 st decoupling level for single bonding | Inductance (L_{bonding}) = 0.8nH one wire: diameter 25 μm , length 1mm |
| 1 st decoupling level to 2 nd decoupling level for single bonding | Inductance (L_{bonding}) = 0.8nH one wire: diameter 25 μm , length 1mm |

DC Schematic

Driver : 5V, 180mA



Notes

Recommended ESD management

Refer to the application note AN0020 available at <http://www.ums-gaas.com> for ESD sensitivity and handling recommendations for the UMS products.

Ordering Information

Chip form:

CHA4105-99F/00

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